



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SC-70</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	520	260 000	200 °C + N2	0	0
HAST	2268	226 800	130 °C, 85 % RH	0	0
Pressure Pot	2486	238 656	121°, 15 PSIG	0	0
Solder DUNK	275	825	260 °C, 10 s	0	0
Solderability	105	840	883 M2003	0	0
Temp. Cycle	4342	2 783 448	-55 °C to 150 °C	0	0